

microfabrication techniques have roots in the standard fabrication methods developed for the semiconductor industry. Some of these techniques are common between the micro/nano and very large-scale integration (VLSI) microchip fabrication disciplines. Lithography is the technique used to transfer a computer-generated pattern onto a substrate (silicon, glass, GaAs, etc.) this pattern is then used to etch

Pulsed laser and atomic layer deposition have attracted a considerable amount of attention recently. These two techniques offer several unique advantages compared with other thin-film deposition. The main advantages of the PLD are its simplicity and ability to deposit complex materials with preserved stoichiometry. Other deposited materials include transition metals (Cu, Co, Fe, and Ni), metal oxide wet

frit can also be used as an interlayer in substrate bonding. A thin layer of glass is deposited and preglazed and the sandwich is heated to above the glass melting temperature. The dimensional spectrum of the microstructures that can be fabricated using these techniques spans from 1 mm to 1 m and a robot based station can take over precise processing and assembly tasks.